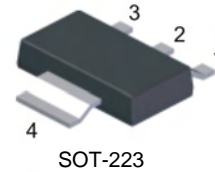


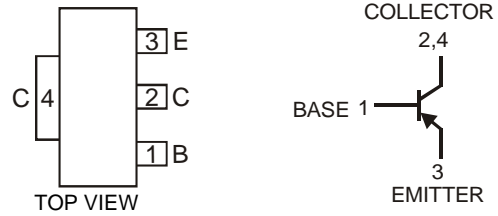
Features

- Epitaxial Planar Die Construction
- Complementary NPN Type Available (DZT651)
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **“Green” Device (Note 2)**



Mechanical Data

- Case: SOT-223
- Case Material: Molded Plastic, “Green” Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Finish – Matte Tin annealed over Copper Leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Marking & Type Code Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.115 grams



Schematic and Pin Configuration

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-80	V
Collector-Emitter Voltage	V_{CEO}	-60	V
Emitter-Base Voltage	V_{EBO}	-5	V
Continuous Collector Current	I_C	-3	A
Peak Pulse Collector Current	I_{CM}	-6	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation @ $T_A = 25^\circ\text{C}$	P_D	1 (Note 3) 2 (Note 4)	W
Thermal Resistance, Junction to Ambient Air (Note 3) @ $T_A = 25^\circ\text{C}$	$R_{\theta JA}$	125	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{STG}	-55 to +150	$^\circ\text{C}$

- Notes:
1. No purposefully added lead.
 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 3. Device mounted on FR-4 PCB, pad layout as shown on last page or in Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>, or on page 4 of this data sheet.
 4. Device mounted on Polyimide PCB with 1.8cm² copper area.

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)						
Collector-Base Breakdown Voltage	$V_{(BR)CBO}$	-80	—	—	V	$I_C = -100\mu\text{A}, I_E = 0$
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	-60	—	—	V	$I_C = -10\text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	-5	—	—	V	$I_E = -100\mu\text{A}, I_C = 0$
Collector Cutoff Current	I_{CBO}	—	—	-0.1	μA	$V_{CB} = -60\text{V}, I_E = 0$
Emitter Cutoff Current	I_{EBO}	—	—	-0.1	μA	$V_{CB} = -60\text{V}, I_E = 0, T_A = 100^\circ\text{C}$
ON CHARACTERISTICS (Note 5)						
Collector-Emitter Saturation Voltage	$V_{CE(SAT)}$	—	-0.08	-0.3	V	$I_C = -1\text{A}, I_B = -100\text{mA}$
		—	-0.2	-0.6	V	$I_C = -3\text{A}, I_B = -300\text{mA}$
Base-Emitter Saturation Voltage	$V_{BE(SAT)}$	—	-0.9	-1.25	V	$I_C = -1\text{A}, I_B = -100\text{mA}$
Base-Emitter Turn-On Voltage	$V_{BE(ON)}$	—	-0.8	-1	V	$V_{CE} = -2\text{V}, I_C = -1\text{A}$
DC Current Gain	h_{FE}	70	200	—	—	$V_{CE} = -2\text{V}, I_C = -50\text{mA}$
		100	180	300	—	$V_{CE} = -2\text{V}, I_C = -500\text{mA}$
		80	160	—	—	$V_{CE} = -2\text{V}, I_C = -1\text{A}$
		40	140	—	—	$V_{CE} = -2\text{V}, I_C = -2\text{A}$
AC CHARACTERISTICS						
Transition Frequency	f_T	100	145	—	MHz	$V_{CE} = -5\text{V}, I_C = -100\text{mA}, f = 100\text{MHz}$
Output Capacitance	C_{obo}	—	—	30	pF	$V_{CB} = -10\text{V}, f = 1\text{MHz}$
Switching Times	t_{on}	—	45	—	ns	$V_{CC} = -10\text{V}, I_C = -500\text{mA}$
	t_{off}	—	200	—	ns	$I_{B1} = I_{B2} = -50\text{mA}$

Notes: 5. Pulse Test: Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2.0\%$.

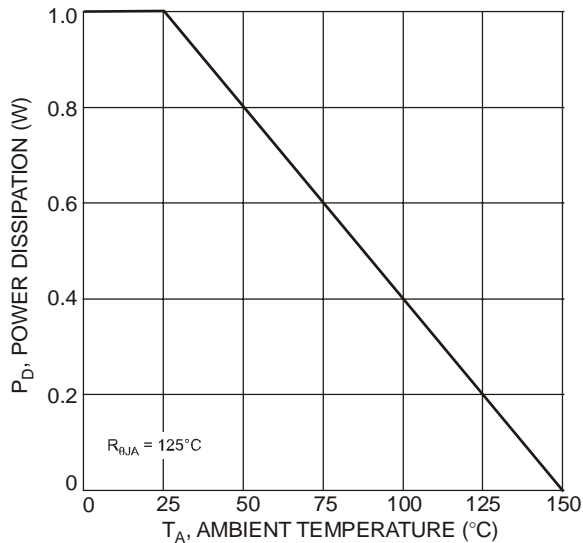


Fig. 1 Power Dissipation vs. Ambient Temperature (Note 3)

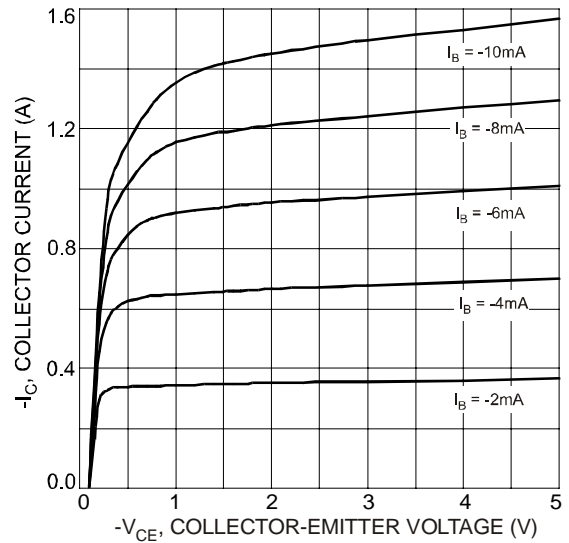


Fig. 2 Typical Collector Current vs. Collector-Emitter Voltage

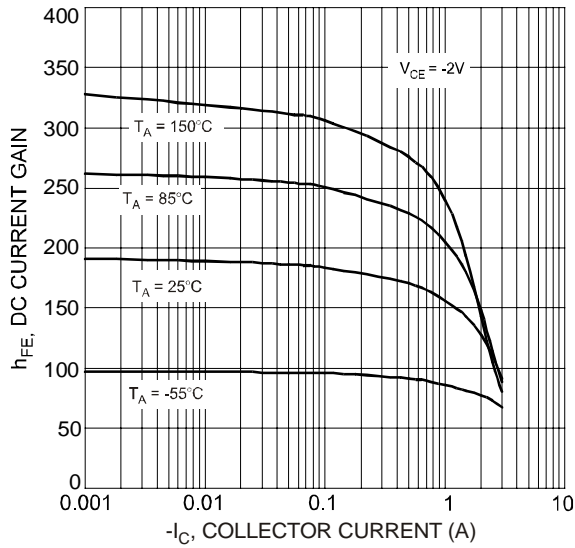


Fig. 3 Typical DC Current Gain vs. Collector Current

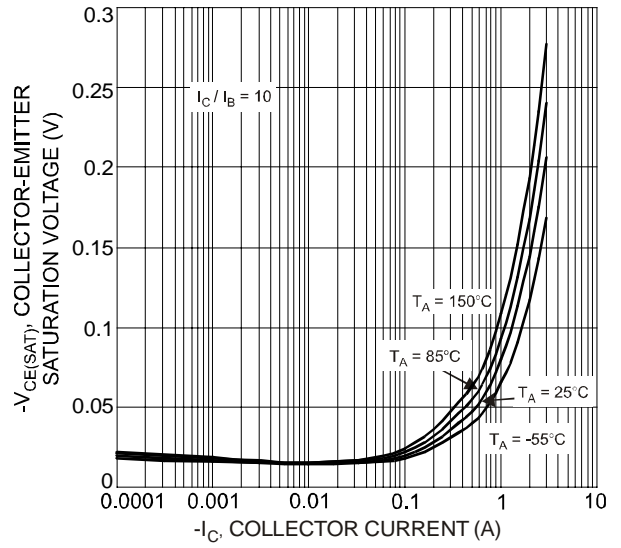


Fig. 4 Typical Collector-Emitter Saturation Voltage vs. Collector Current

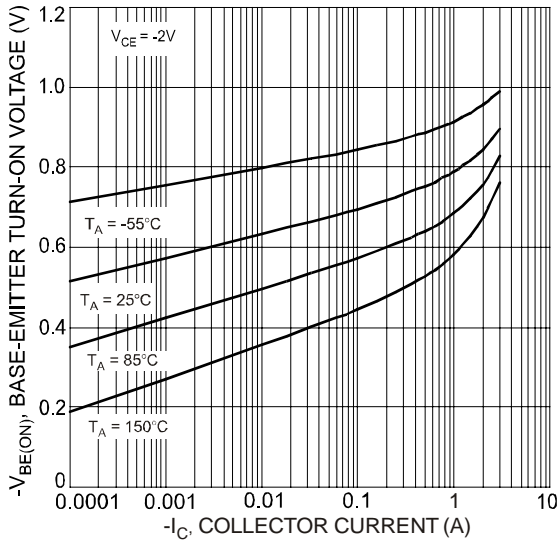


Fig. 5 Typical Base-Emitter Turn-On Voltage vs. Collector Current

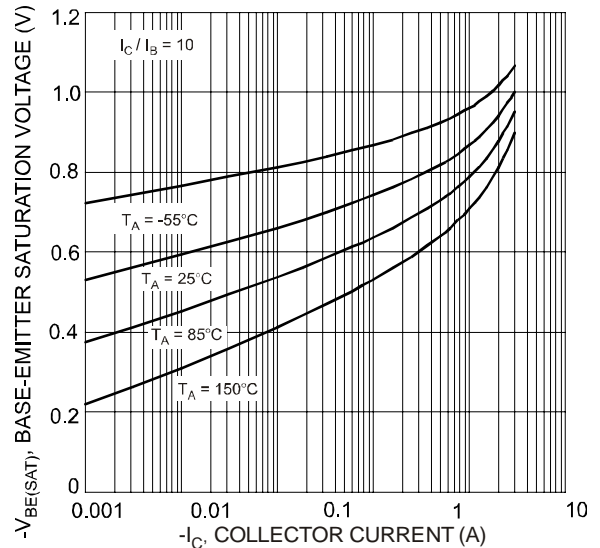


Fig. 6 Typical Base-Emitter Saturation Voltage vs. Collector Current

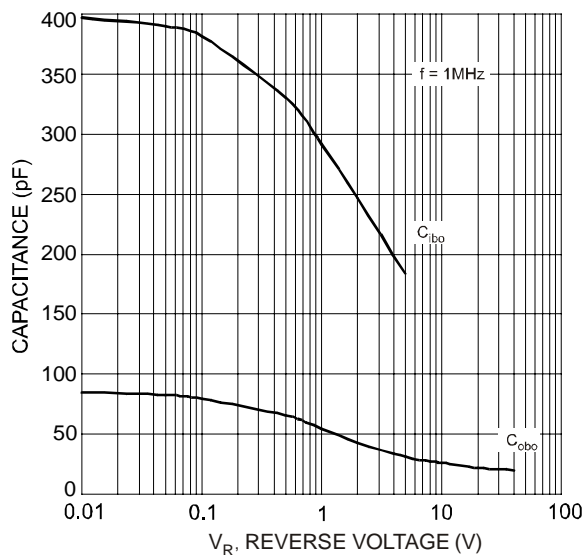


Fig. 7 Typical Capacitance Characteristics

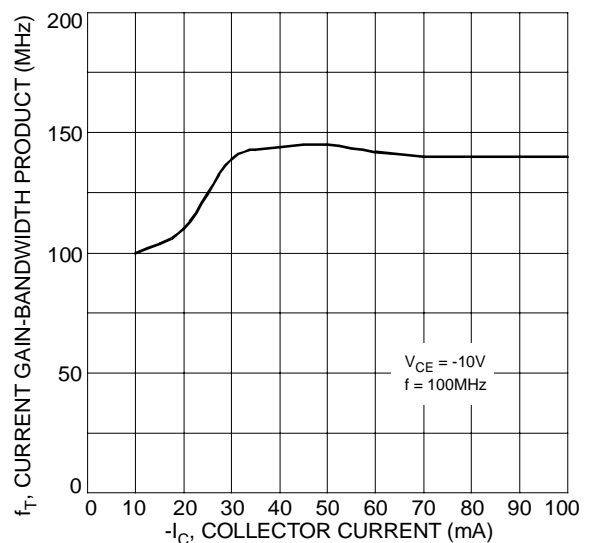


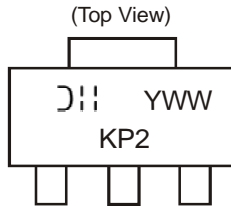
Fig. 8 Typical Gain-Bandwidth Product vs. Collector Current

Ordering Information (Note 6)

Device	Packaging	Shipping
DZT751-13	SOT-223	2500/Tape & Reel

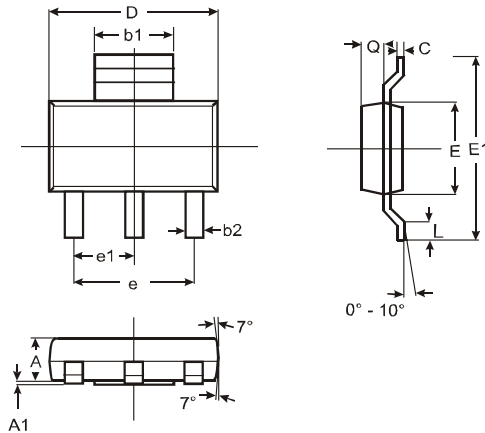
Notes: 6. For packaging details, please go to our website at <http://www.diodes.com/ap02007.pdf>.

Marking Information



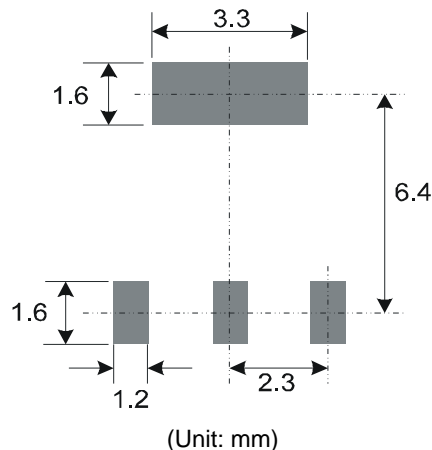
KP2 = Product Type Marking Code
 YWW = Date Code Marking
 Y = Last digit of year ex: 7 = 2007
 WW = Week code 01 - 52

Package Outline Dimensions



SOT-223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b1	2.90	3.10	3.00
b2	0.60	0.80	0.70
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	—	—	4.60
e1	—	—	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89
All Dimensions in mm			

Suggested Pad Layout



IMPORTANT NOTICE

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. Diodes Incorporated does not assume any liability arising out of the application or use of any product described herein; neither does it convey any license under its patent rights, nor the rights of others. The user of products in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on our website, harmless against all damages.

LIFE SUPPORT

Diodes Incorporated products are not authorized for use as critical components in life support devices or systems without the expressed written approval of the President of Diodes Incorporated.

单击下面可查看定价，库存，交付和生命周期等信息

[>>Diodes Incorporated\(达达科技\(美台\)\)](#)